

Mattson AST2900



Mattson's 2900 RTP systems are widely employed by chip manufacturers worldwide. The 2900 is a robust workhorse based on the production-proven 2800 RTP system, combining its reliability and low cost of ownership with the latest advances in process performance.

Mattson's unique dual-side wafer heating and a contact-less edge-guard ring that surrounds the wafer on the wafer-level provide the highest wafer yields and best process results.

This proprietary dual-wafer heating technology provides minimized thermal stress and strain in the wafer, virtually no wafer warpage and, most importantly, the reduction of pattern effects.

Our Ripple™-based temperature measurement, with its emissivity compensation feature, ensures highly accurate and repeatable temperature measurement. The independent lamp control provides excellent temperature uniformity across the wafer. The 2900 offers a wide range of process applications that meet the stringent manufacturing requirements of devices down to 130 nm technology node.

The system's very small footprint, dual-arm robot for optimized wafer handling and improved chamber throughput offer unparalleled cost of ownership benefits. The 2900 is available for 200 mm and 150 mm wafer sizes.

RTP 2900 Description

- Manufactured (2001,2002,2003) Made in Germany
- 200mm (easily changed to 150mm)
- DSM Computer
- SECS/GEM HSMS
- Dual blade Rorze robot
- Thin type end effector
- 38 lamps
- 2 Cassette nests
- Flat aligner
- Pre heat dummy station
- Slot sensor
- 2x 3-color lamp tower
- Smoke detector
- Mini environment monitor
- O2 sensor
- Front GUI interface – stand alone
- Chamber door heater
- Deionization kit









